Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP G42 Notebook PC

Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board, Touch pad</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack, Coin cell battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0
Components and waste containing asbestos | 0
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1Screwdriver</td>
<td>Type-cross #1 (JIS B 4633-1987)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble main battery
2. Disassemble ram door & hdd door
3. Dis-fasten BASE screw*18(M2.5*3,M2.5*5,M2.5*6.5)
4. Pull out hdd cable
5. Dis-fasten hdd screw*3(M2.5*5)
6. Disassemble HDD ASSY
7. Dis-fasten hdd bracket screw*4(M3*3.5)
8. Remove HDD
9. Dis-fasten base screw*1(M2.5*3)
10. Pull out WLAN cables
11. Dis-fasten WLAN module screw*1(M2*3)
12. Remove WLAN module
13. Remove RAM module from Mainboard
14. Remove ODD ASSY
15. Remove ODD from ODD ASSY
16. Pull out Keyboard membrane
17. Remove Keyboard
18. Dis-fasten TOP screw*1(M2.5*5)
19. Pull out speaker cable
20. Pull out power FFC, Touchpad FFC & TP button FFC
21. Disassemble TOP ASSY
22. Dis-fasten speaker screw*2(M2.5*3)
23. Disassemble speaker
24. Pull out LCD cable, MIC cable, CCD cable, Bluetooth cable, ODD cable, Modem cable, DC cable & USB FFC
25. Dis-fasten Modem screw*2(M2*3)
26. Remove Modem module
27. Dis-fasten LCD ASSY screw*4(M2.5*6.5)
28. Disassemble LCD ASSY
29. Dis-fasten Mainboard & FAN module screw*3(M2.5*4)
30. Disassemble Mainboard
31. Dis-fasten fan screw*6
32. Remove FAN module
33. Disassemble CPU
34. Remove screw mylar*2
35. Dis-fasten LCD BEZEL screw*2(M2.5*3)
36. Disassemble LCD BEZEL
37. Dis-fasten hinge cover screw*2(M2.5*4)
38. Remove hinge cover*2
39. Dis-fasten hinge screw*6(M2.5*4)
40. Disassemble panel with hinge bracket
41. Dis-fasten hinge bracket screw*4(M2*3)
42. Remove hinge bracket
43. Pull out LCD cable

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
LCD panel disassembly process

1. Remove tape, cover film and screw
2. Remove bezel
3. Remove Cell
4. Remove films
5. Remove LGP & white sheet
6. Separate LED reflector from frame
7. Remove tape
8. Separate LED light bar
9. LED light bar